

Application No.: 10/776,227Docket No.: 4459-139**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor package, comprising:
a carrier lead frame having a die pad, a plurality of inner leads and a plurality of outer leads electrically connected to the inner leads for being electrically connected to an external circuit;
a plurality of first spacers disposed on the carrier die pad;
a first chip disposed on the first spacers and defining an active surface and a back surface;
~~a plurality of contacts disposed on the carrier for being electrically connected to an external circuit;~~
a plurality of first bonding wires ~~[[for]]~~ electrically connecting the first chip to the ~~contacts~~ inner leads; and
an encapsulant encapsulating the first spacers, the active surface and the back surface of the first chip, and the first bonding wires.

2-3. (canceled)

4. (currently amended) A semiconductor package, comprising:
a carrier;
a plurality of first spacers disposed on the carrier;
a first chip disposed on the first spacers and having an active surface and a back surface;
a plurality of contacts disposed on the carrier for being electrically connected to an external

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circuit:

a plurality of first bonding wires electrically connecting the first chip to the contacts; and
an encapsulant encapsulating the first spacers, the active surface and the back surface of the
first chip, and the first bonding wires;

~~The semiconductor package as claimed in claim 1,~~ wherein the carrier is a lead frame having a die pad on which the first spacers are disposed.

5. (canceled)

6. (currently amended) The semiconductor package as claimed in claim 1, further comprising:

a plurality of second spacers disposed on the first chip;
a second chip disposed on the second spacers; and
a plurality of second bonding wires ~~[[for]]~~ electrically connecting the second chip to the contacts inner leads,

wherein the encapsulant further encapsulates the second spacers, the second chip, and the second bonding wires.

7. (currently amended) The semiconductor package as claimed in claim 1, further comprising a plurality of adhesives mixed with the spacers and disposed on the carrier lead frame.

8-13. (canceled)